

Improved surface and interface properties of InP

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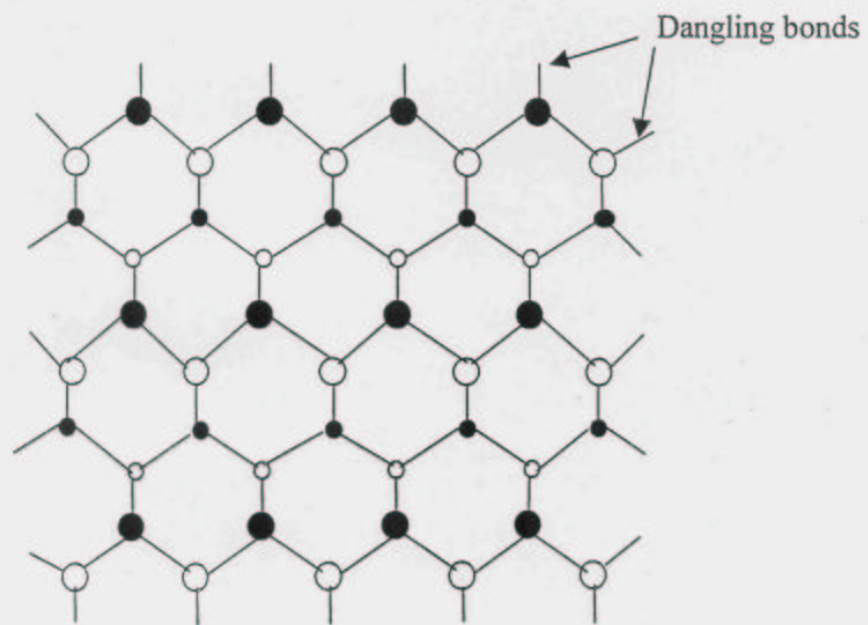


Figure 1.1 Zinc-blende lattice projected on (110) face showing the dangling bonds on the surface

Problem addressed:

- **Surface Fermi-level pinning is a very serious problem in indium phosphide.**
- **The Fermi-level pinning limits the rapid development of InP based devices.**

Possible solution for the problem:

- **To reduce the surface states, thereby unpin the Fermi-level in indium phosphide (InP) by proper surface preparation and effective passivation schemes**

Our approach:

Surface polishing:

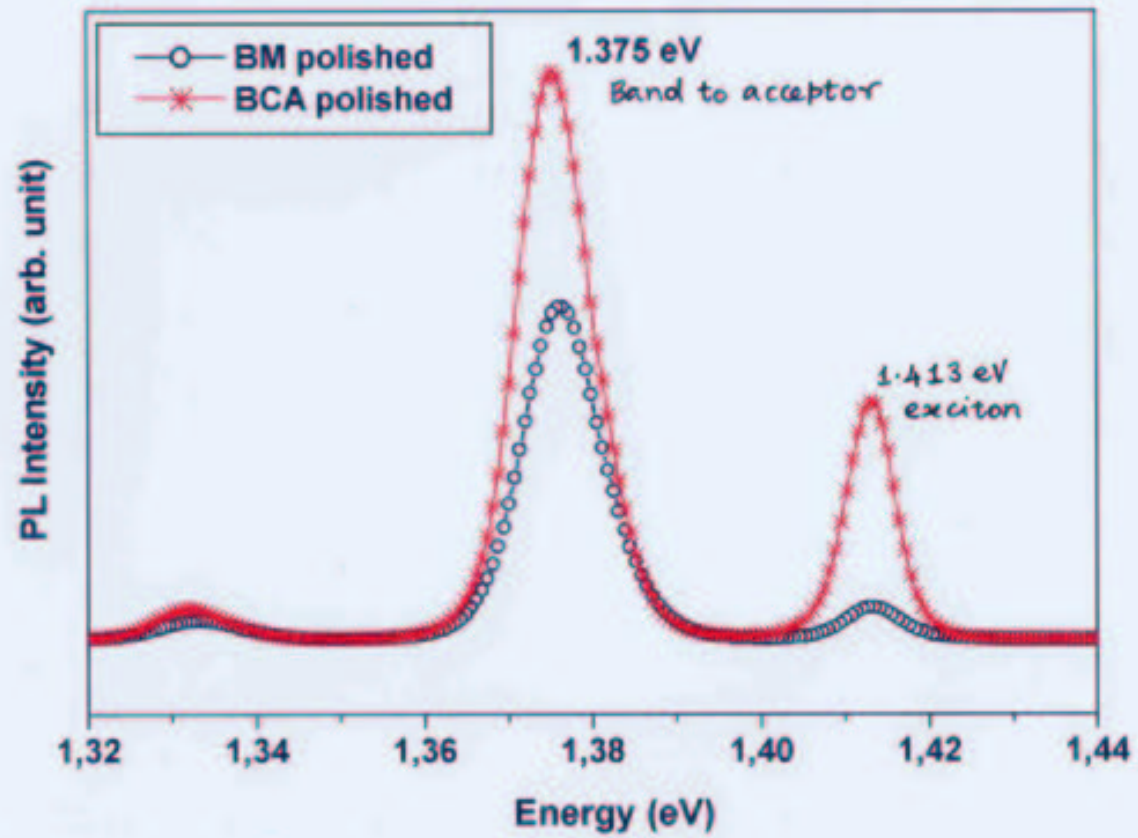
- **A new polishing solution, $\text{HBr}:\text{K}_2\text{Cr}_2\text{O}_7:\text{H}_2\text{O}$ (BCA) has been developed and it has been compared with conventional bromine-methanol (BM) solution.**

Surface passivation:

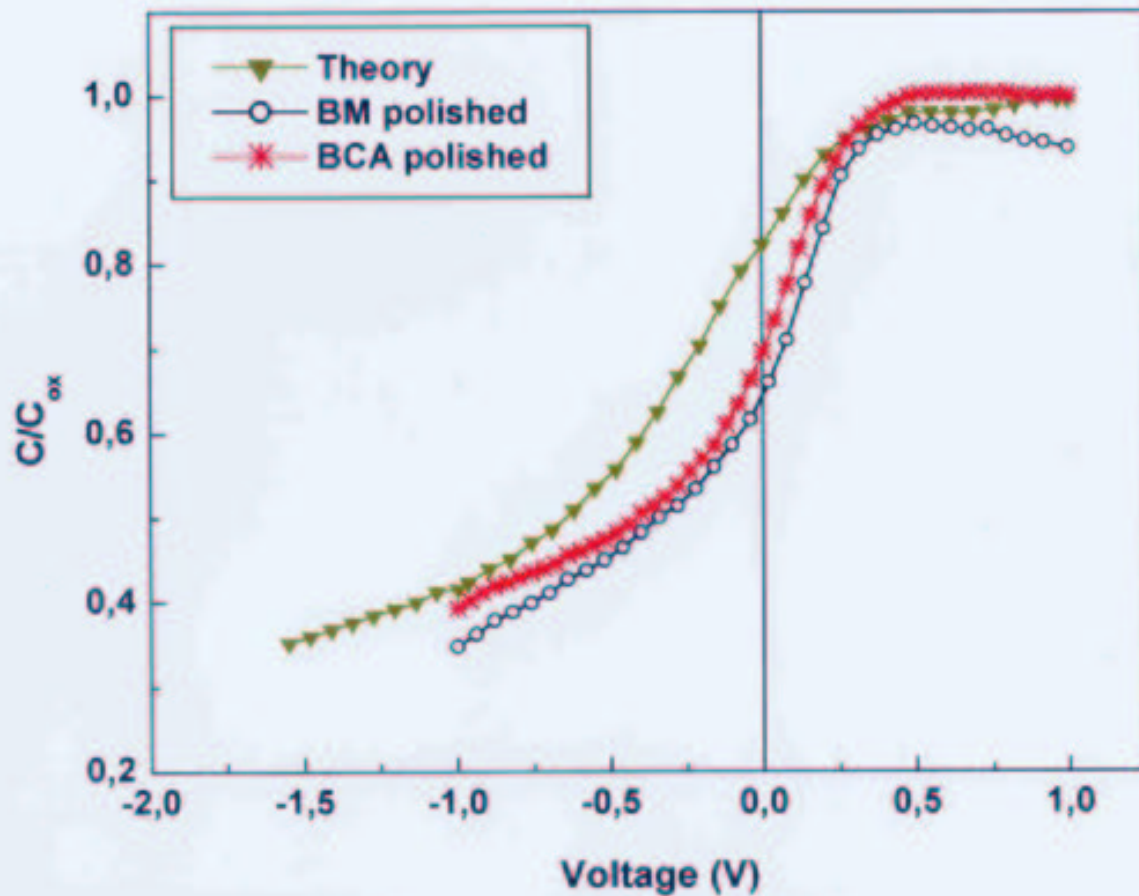
- **Cadmium sulfide (CdS) has been identified as a better passivating agent for InP and CdS passivation has been carried out using simple chemical bath deposition (CBD) method.**

CdS passivation mechanism:

- **As the bonding in InP is mainly covalent, there will be a large perturbation of the valence-state energy at the surface**
- **But constituents of II-VI compounds have a larger electro negativity difference, indicating that the bonds are ionic in nature**
- **the electron wave functions of the ions do not overlap sufficiently to induce midgap states**
- **Thus insulator/II-VI interface should behave more ideally than insulator/III-V counterpart**



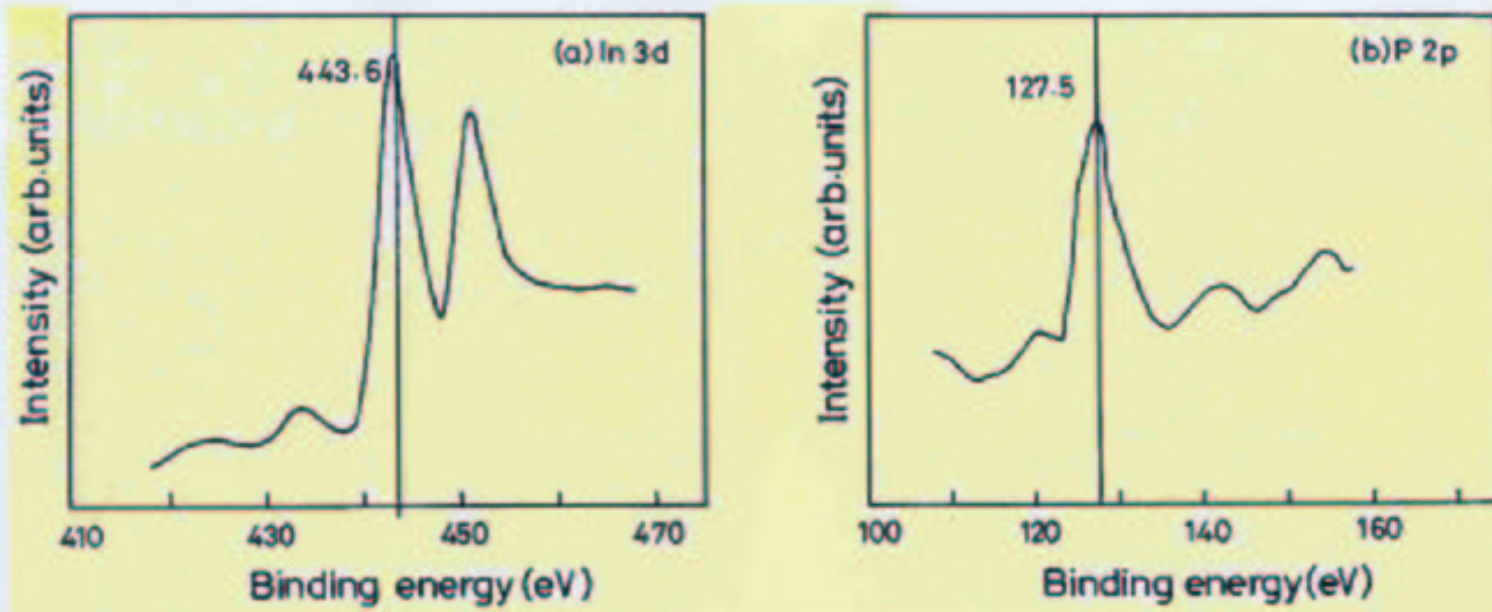
LT *PL spectra of (a) BCA and BM polished InP surface*



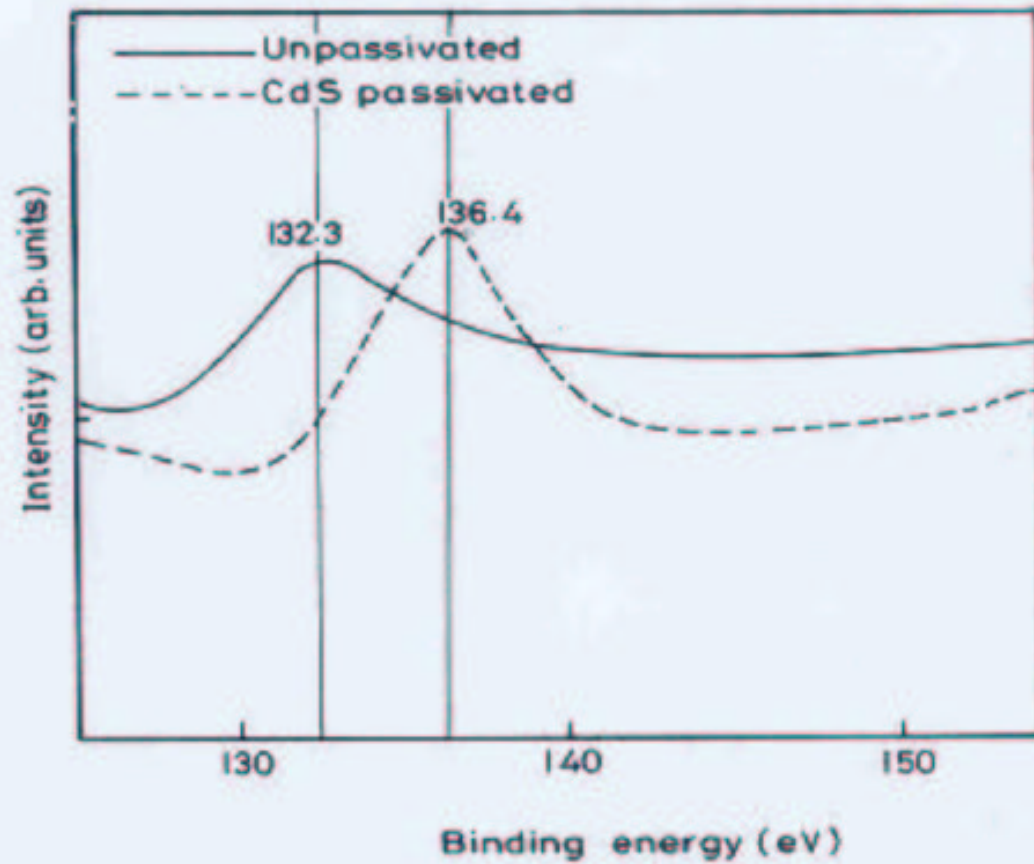
For BM polished Sample,
 $N_{ss} = 9 \times 10^{10} \text{ cm}^{-2} \text{ eV}^{-1}$

For BCA Polished Sample,
 $N_{ss} = 6 \times 10^{10} \text{ cm}^{-2} \text{ eV}^{-1}$

Theoretical and experimental C-V curves for N_{ss} calculation



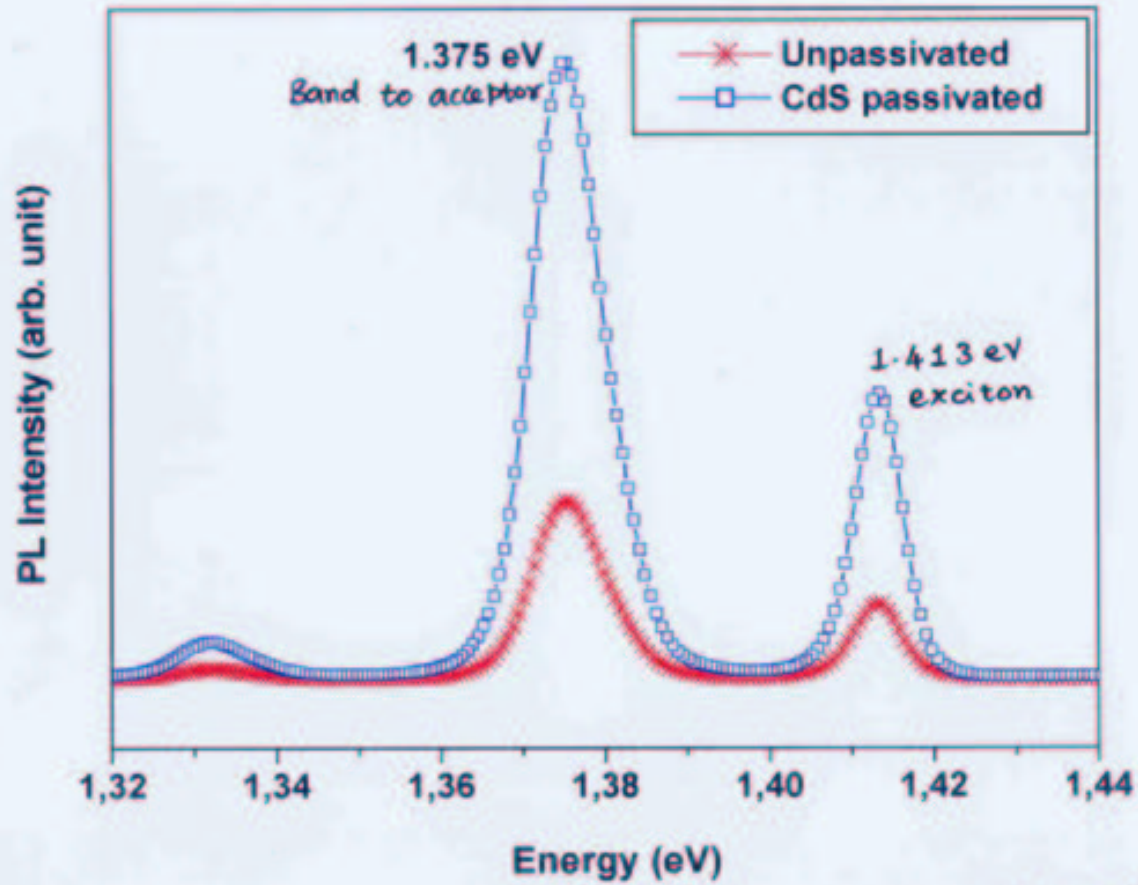
XPS spectra of CdS passivated InP showing the absence of native oxides



XPS spectra of P 2p peak of unpassivated and CdS passivated InP

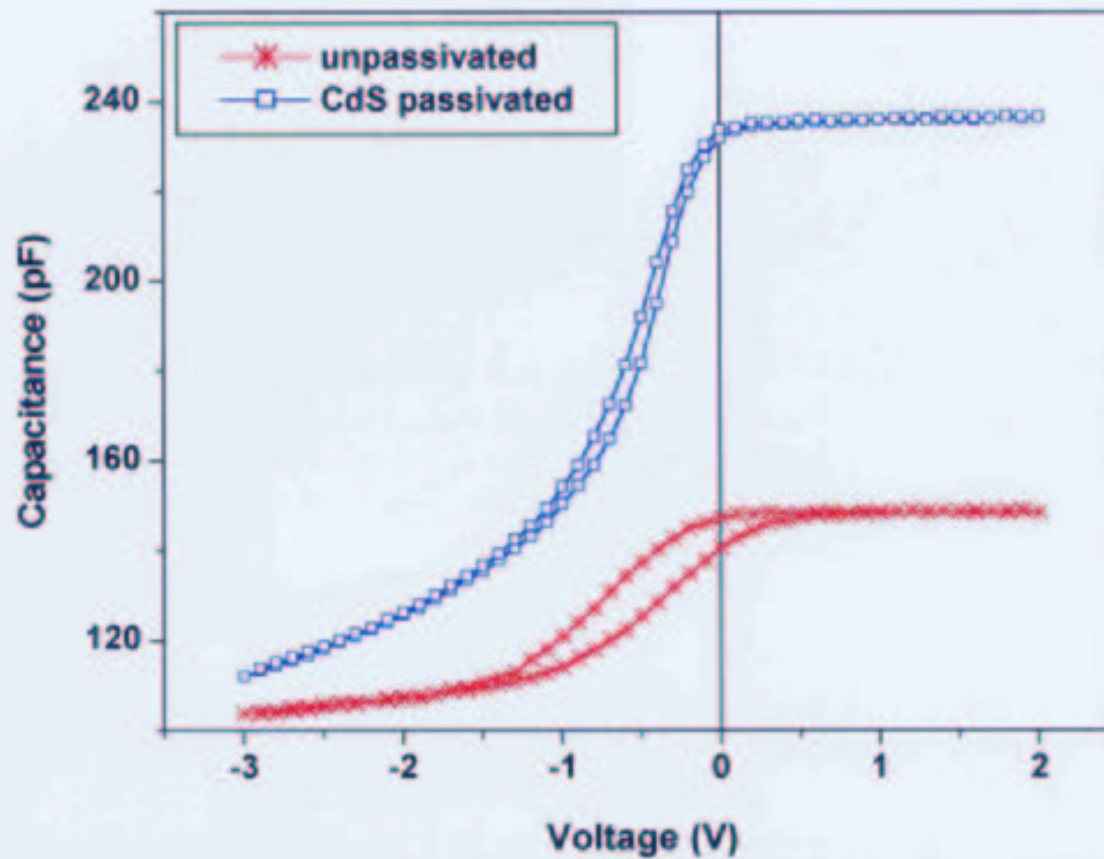
Possible mechanism for formation of P_2O_5 :

- **During anodic oxidation of InP, both indium oxide (In_2O_3) and phosphorus oxide (P_2O_5) can be formed. In_2O_3 is conductive oxide, whereas P_2O_5 is a high resistive oxide.**
- **After passivation, the sulfur atoms in the CdS substitutes the oxygen atoms present in In_2O_3 and thereby forming In_2S_3 .**
- **Thus the formation of In_2O_3 is suppressed and further this In_2S_3 is dissolvable in the electrolyte. Hence P_2O_5 formation is enhanced and formation of high resistive layer is accomplished**

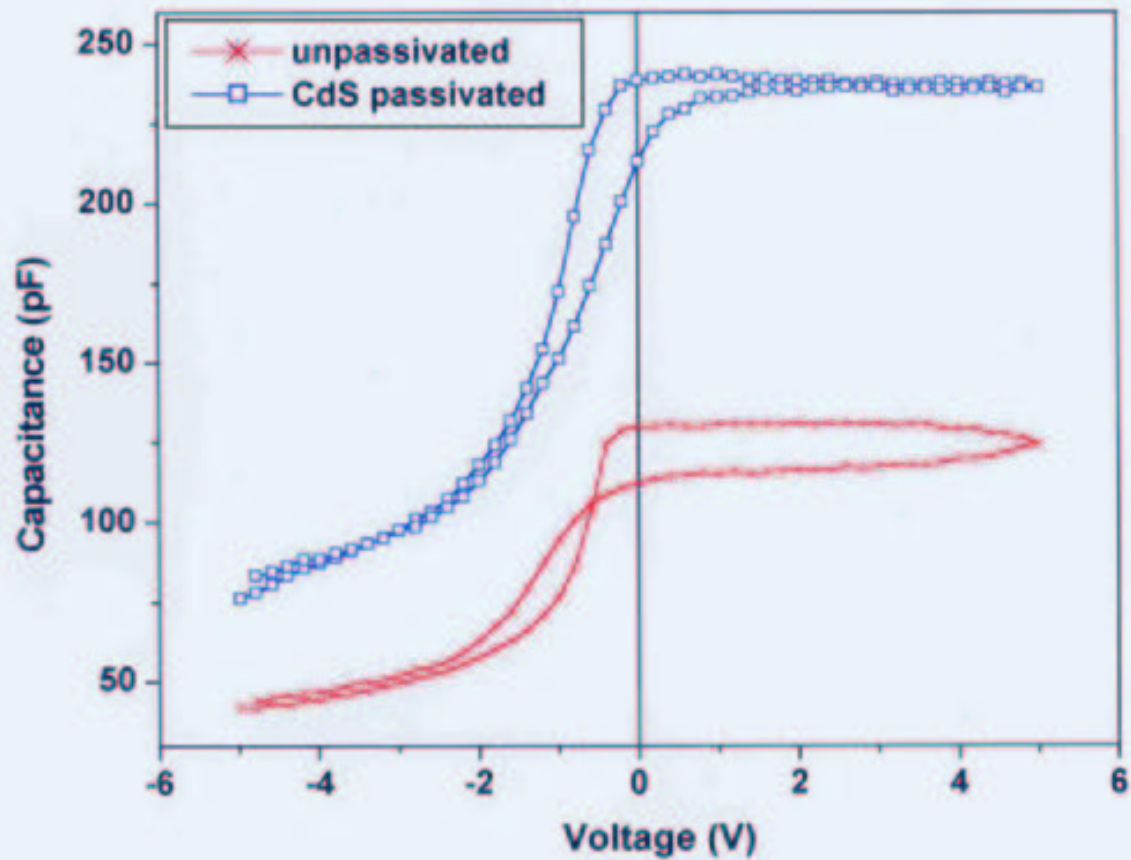


Enhanced PL intensity for BCA polished InP

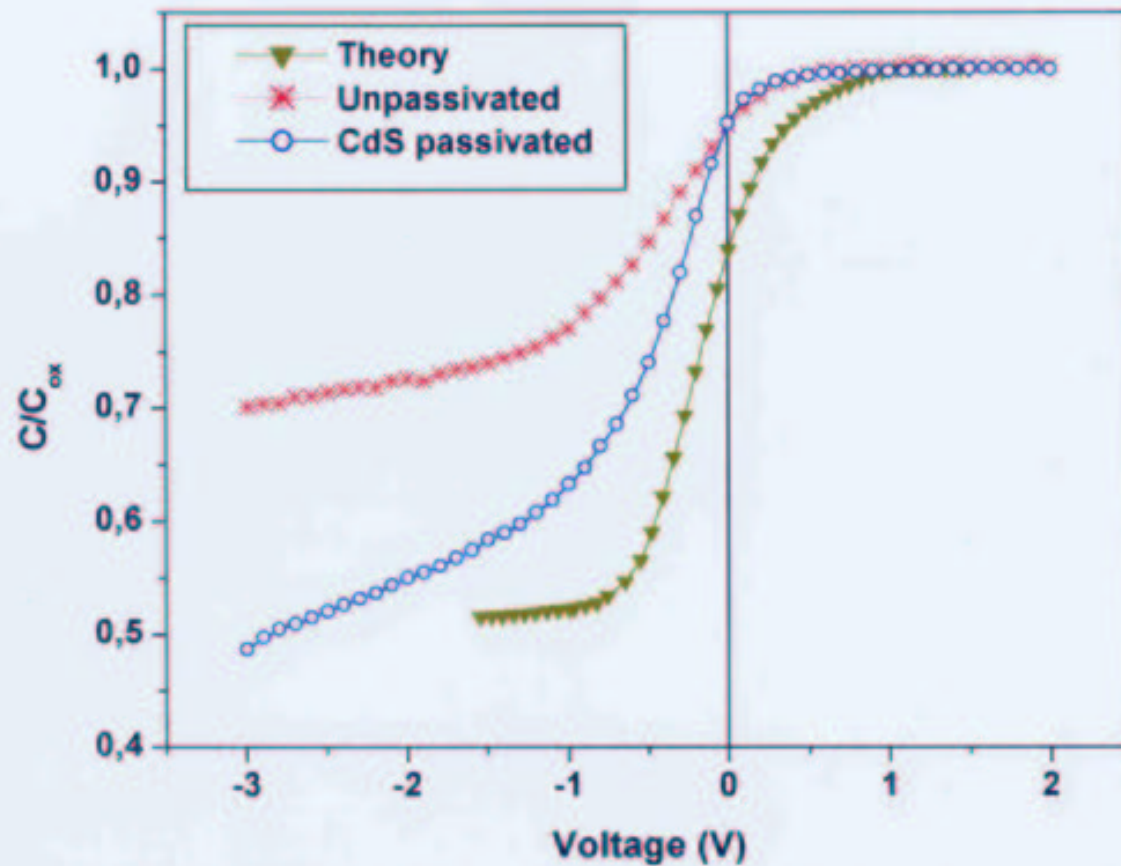
CdS passivated



1 MHz C-V curves for unpassivated and CdS passivated MIS diodes



C-V curve of the passivated sample shows the high stability even in higher bias values



For the Unpassivated InP Sample,

$$N_{ss} = 6 \times 10^{10} \text{ cm}^{-2} \text{ eV}^{-1} \text{ (mid gap)}$$

$$4 \times 10^{11} \text{ cm}^{-2} \text{ eV}^{-1} \text{ (band edge)}$$

For passivated InP,

$$N_{ss} \approx 10^{10} \text{ cm}^{-2} \text{ eV}^{-1} \text{ (throughout the band gap)}$$

C-V curve of the passivated sample follows very good with the theoretical curve, unlike unpassivated sample

Conclusions:

- **The surface states have been reduced, thereby reducing the surface Fermi-level pinning in InP by proper surface polishing and effective surface passivation processes**
- **A new polishing solution (BCA) has been established and it acts as a better self-passivating agent to reduce the surface states ($N_{SS} = 6 \times 10^{10} \text{ cm}^{-2} \text{ eV}^{-1}$)**
- **By CdS passivation the surface states have been further reduced ($N_{SS} = 10^{10} \text{ cm}^{-2} \text{ eV}^{-1}$), thus reducing the Fermi-level pinning.**
- **The new polishing and passivation mechanism has been analysed and understood. The methods employed in this work are simple and very cost effective**